

L Number	Hits	Search Text	DB	Time stamp
1	1	6168837.pn.	USPAT; US-PGPUB	2003/11/30 16:26
2	2955	((427/248.1,255.23,255.28,255.7,587).CCLS.	USPAT; US-PGPUB	2003/11/30 16:26
3	5484	((118/715,719,724,725,728).CCLS.	USPAT; US-PGPUB	2003/11/30 16:26
4	1272	((117/84,85,88,105,200,201).CCLS.	USPAT; US-PGPUB	2003/11/30 16:27
5	9120	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)	USPAT; US-PGPUB	2003/11/30 16:27
6	8	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) near4 wall)	USPAT; US-PGPUB	2003/11/30 16:46
7	12	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) near6 wall)	USPAT; US-PGPUB	2003/11/30 16:29
8	4	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) near6 wall)) not (((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) near4 wall))	USPAT; US-PGPUB	2003/11/30 16:29
9	25	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) and ((heat\$3 or temperature) near3 wall) and ((heat\$3 or temperature) near3 (support or susceptor or substrate or base or wafer))	USPAT; US-PGPUB	2003/11/30 16:39
10	57	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) and ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall))	USPAT; US-PGPUB	2003/11/30 16:41
11	15	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall))	USPAT; US-PGPUB	2003/11/30 16:47
12	21	((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj deposit\$3 or epitax\$6))) and ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (heat\$3 or cool\$3 or temperature))	USPAT; US-PGPUB	2003/11/30 16:44

13	16	(((((427/248.1,255.23,255.28,255.7,587).CCLS. ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) and ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (heat\$3 or cool\$3 or temperature)))) not (((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall))))))	USPAT; US-PGPUB	2003/11/30 16:44
14	29	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) near4 wall)	USPAT; US-PGPUB	2003/11/30 17:00
15	21	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) near4 wall)) not (((427/248.1,255.23,255.28,255.7,587).CCLS.) ((118/715,719,724,725,728).CCLS.) ((117/84,85,88,105,200,201).CCLS.)) and ((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) near6 wall))	USPAT; US-PGPUB	2003/11/30 16:46
16	6	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	USPAT; US-PGPUB	2003/11/30 17:00
17	96	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	USPAT; US-PGPUB	2003/11/30 16:59
18	90	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3))) not (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3))))	USPAT; US-PGPUB	2003/11/30 16:49
19	10	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	USPAT; US-PGPUB	2003/11/30 16:58

20	8	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (wall) with (hot or cold or temperature or heat\$3 or cool\$3)))) not (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3))))	USPAT; US-PGPUB	2003/11/30 16:49
21	11	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with ((minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3))))	USPAT; US-PGPUB	2003/11/30 16:58
22	9	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with ((minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))) not (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (wall) with (hot or cold or temperature or heat\$3 or cool\$3)))) or (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3))))	USPAT; US-PGPUB	2003/11/30 16:51
23	44	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with ((minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall)))	USPAT; US-PGPUB	2003/11/30 16:56
24	35	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with ((minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall))) not (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with ((minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))) not (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (wall) with (hot or cold or temperature or heat\$3 or cool\$3)))) or (((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3))))	USPAT; US-PGPUB	2003/11/30 16:52

25	6	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) and ((wall with (substrate or support or base or susceptor or wafer) with (higher or lower or different or difference) with (temperature))))	USPAT; US-PGPUB	2003/11/30 16:56
26	0	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) and ((wall with (substrate or support or base or susceptor or wafer) with (higher or lower or different or difference) with (temperature))))	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 16:56
27	12	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall)))	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 16:56
28	2	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) with (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 16:58
29	1	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 16:58
30	14	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 16:59
31	0	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) same ((deposit\$3 or decompos\$5 or condens\$5 or contaminat\$4 or coat\$3) near3 (minimiz\$5 or eliminat\$3 or prevent\$3 or avoid\$5) with (chamber or vessel or reactor or wall) with (hot or cold or temperature or heat\$3 or cool\$3)))	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 17:00
32	6	((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$6))) near4 wall)	EPO; JPO; DERWENT; IBM_TDB	2003/11/30 17:00
-	2	6562140.pn. or 6579374.pn.	USPAT; US-PGPUB	2003/11/26 11:21
-	1	6630030.pn.	USPAT; US-PGPUB	2003/11/26 11:22
-	2	(ASM.as. or Lindfors.in. or Bondestam.in.) and ((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$5))) same ((control\$5 or regulat\$3 or optimiz\$5 or monitor\$3) near3 wall near3 temperature))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/26 11:26
-	7	(ASM.as. or Lindfors.in. or Bondestam.in.) and ((ALE or ALD or (atomic adj layer adj (deposit\$3 or epitax\$5))) and (substrate near5 temperature) and (wall near5 temperature))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 16:24